

MC10H165

8-Input Priority Encoder

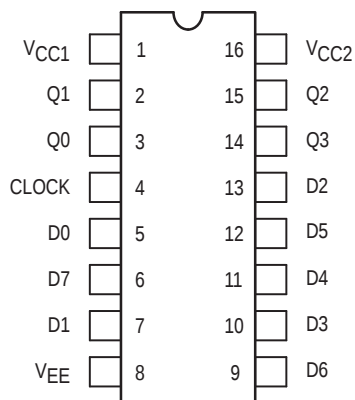
The MC10H165 is an 8-Input Priority Encoder. This 10H part is a functional/pinout duplication of the standard MECL 10K family part, with 100% improvement in propagation delay, and no increases in power-supply current.

- Propagation Delay, Data-to-Output, 2.2 ns Typical
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K-Compatible

TRUTH TABLE

DATA INPUTS								OUTPUTS			
D0	D1	D2	D3	D4	D5	D6	D7	Q3	Q2	Q1	Q0
H	X	X	X	X	X	X	X	H	L	L	L
L	H	X	X	X	X	X	X	H	L	L	H
L	L	H	X	X	X	X	X	H	L	H	L
L	L	L	H	X	X	X	X	H	L	L	H
L	L	L	L	H	X	X	X	H	H	L	L
L	L	L	L	L	H	X	X	H	H	H	L
L	L	L	L	L	L	H	X	H	H	H	H
L	L	L	L	L	L	L	H	L	L	L	L

DIP
PIN ASSIGNMENT



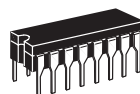
Pin assignment is for Dual-in-Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18
of the ON Semiconductor MECL Data Book (DL122/D).



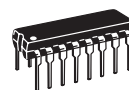
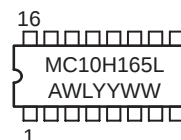
ON Semiconductor

<http://onsemi.com>

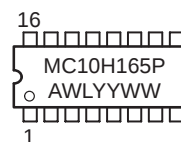
MARKING
DIAGRAMS



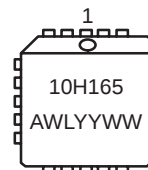
CDIP-16
L SUFFIX
CASE 620



PDIP-16
P SUFFIX
CASE 648



PLCC-20
FN SUFFIX
CASE 775



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping
MC10H165L	CDIP-16	25 Units/Rail
MC10H165P	PDIP-16	25 Units/Rail
MC10H165FN	PLCC-20	46 Units/Rail

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MAXIMUM RATINGS

Symbol	Characteristic	Rating	Unit
V_{EE}	Power Supply ($V_{CC} = 0$)	-8.0 to 0	Vdc
V_I	Input Voltage ($V_{CC} = 0$)	0 to V_{EE}	Vdc
I_{out}	Output Current – Continuous – Surge	50 100	mA
T_A	Operating Temperature Range	0 to +75	°C
T_{stg}	Storage Temperature Range – Plastic – Ceramic	-55 to +150 -55 to +165	°C

ELECTRICAL CHARACTERISTICS ($V_{EE} = -5.2\text{ V} \pm 5\%$) (See Note 1.)

Symbol	Characteristic	0°		25°		75°		Unit
		Min	Max	Min	Max	Min	Max	
I_E	Power Supply Current	–	144	–	131	–	144	mA
I_{inH}	Input Current High Pin 4	–	510	–	320	–	320	μA dc
	Data Inputs	–	600	–	370	–	370	
I_{inL}	Input Current Low	0.5	–	0.5	–	0.3	–	μA
V_{OH}	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
V_{OL}	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
V_{IH}	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
V_{IL}	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

AC PARAMETERS

t_{pd}	Propagation Delay							ns
	Data Input Output Clock Input Output	0.7 0.7	3.4 2.2	0.7 0.7	3.4 2.2	0.7 0.7	3.4 2.2	
t_{set}	Set-up Time	3.0	–	3.0	–	3.0	–	ns
t_{hold}	Hold Time	0.5	–	0.5	–	0.5	–	ns
t_r	Rise Time	0.5	2.4	0.5	2.4	0.5	2.4	ns
t_f	Fall Time	0.5	2.4	0.5	2.4	0.5	2.4	ns

- Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts.

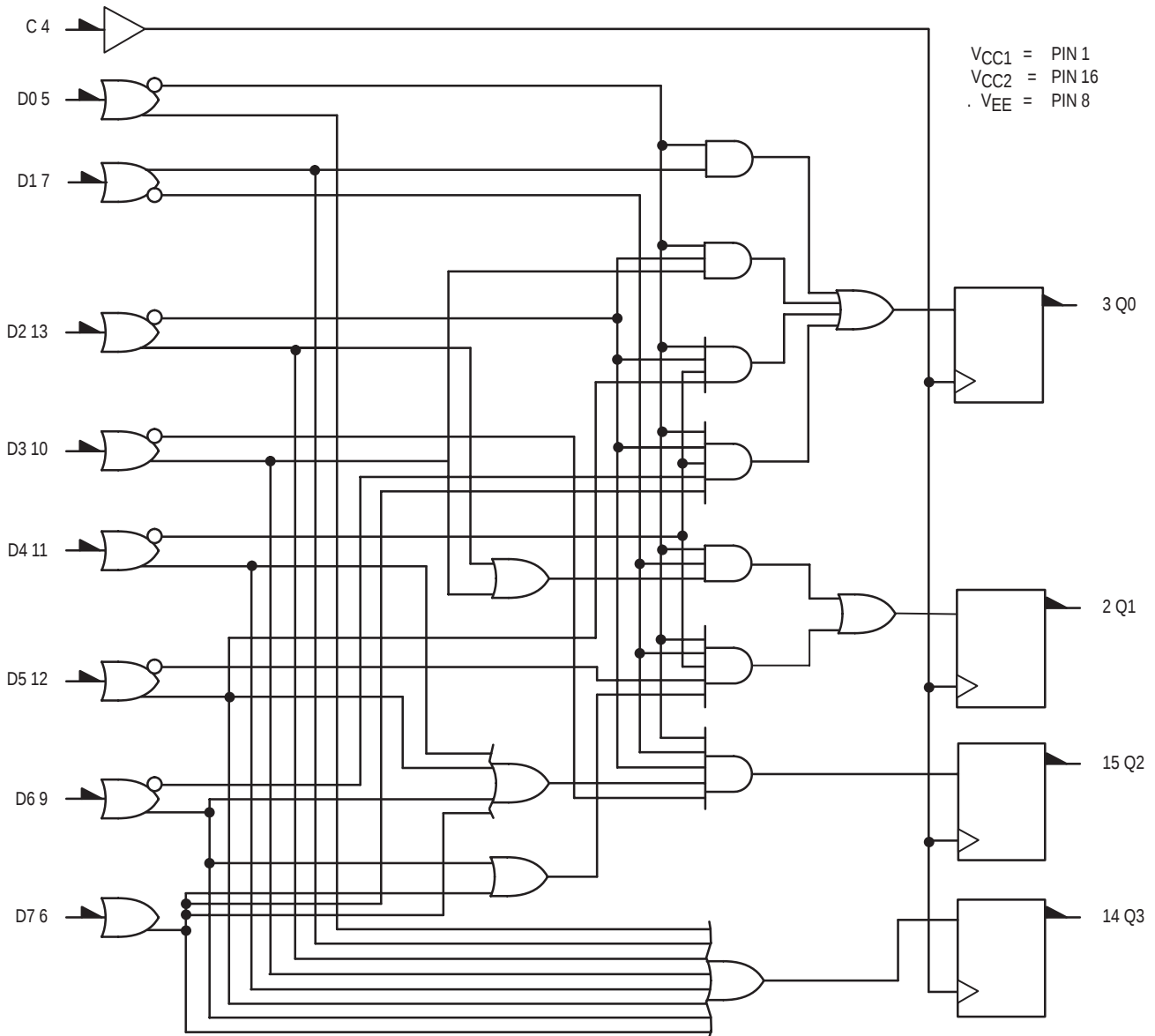
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8-INPUT PRIORITY ENCODER

The MC10H165 is a device designed to encode eight inputs to a binary coded output. The output code is that of the highest order input. Any input of lower priority is ignored. Each output incorporates a latch allowing synchronous operation. When the clock is low the outputs follow the inputs and latch when the clock goes high. This device is very useful for a variety of applications in checking system status in control processors, peripheral controllers, and testing systems.

The input is active when high, (e.g., the three binary outputs are low when input D0 is high). The Q3 output is high when any input is high. This allows direct extension into another priority encoder when more than eight inputs are necessary. The MC10H165 can also be used to develop binary codes from random logic inputs, for addressing ROMs, RAMs, or for multiplexing data.

LOGIC DIAGRAM

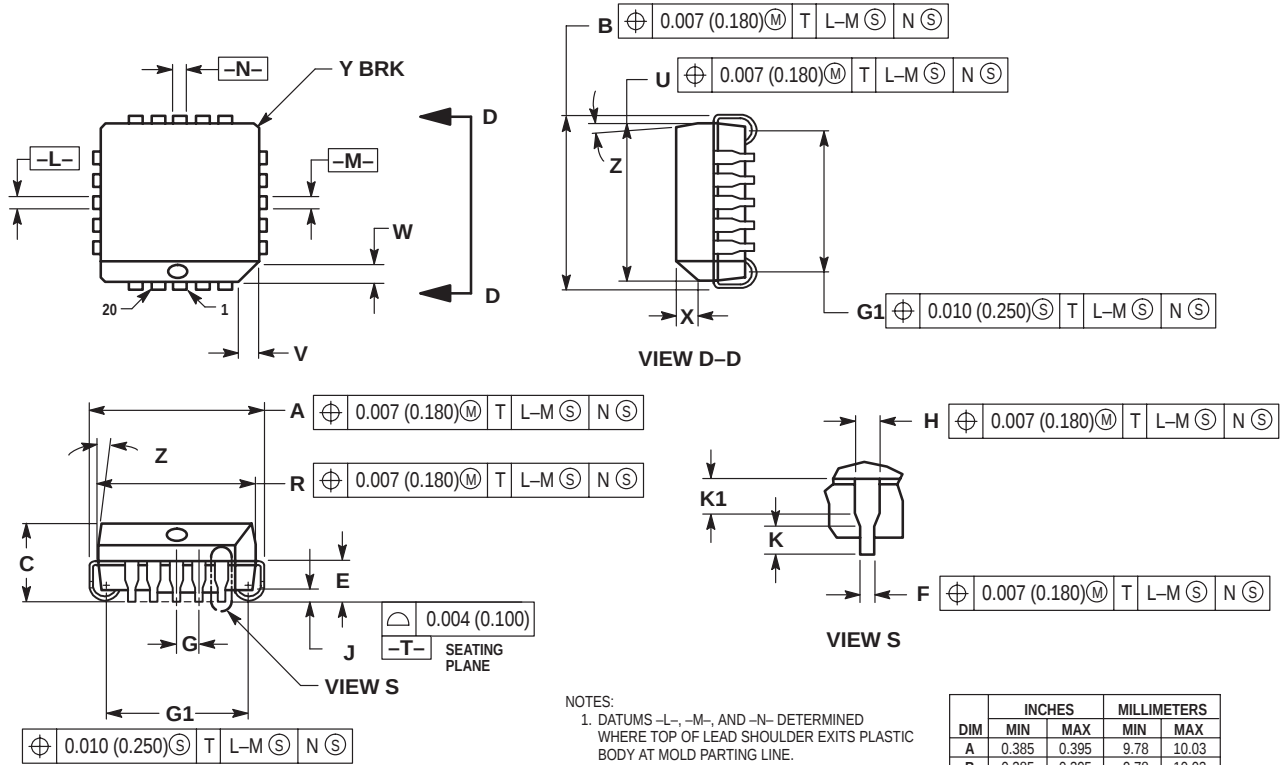


Numbers at ends of terminals denote pin numbers for L and P packages.

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PACKAGE DIMENSIONS

PLCC-20
FN SUFFIX
PLASTIC PLCC PACKAGE
CASE 775-02
ISSUE C



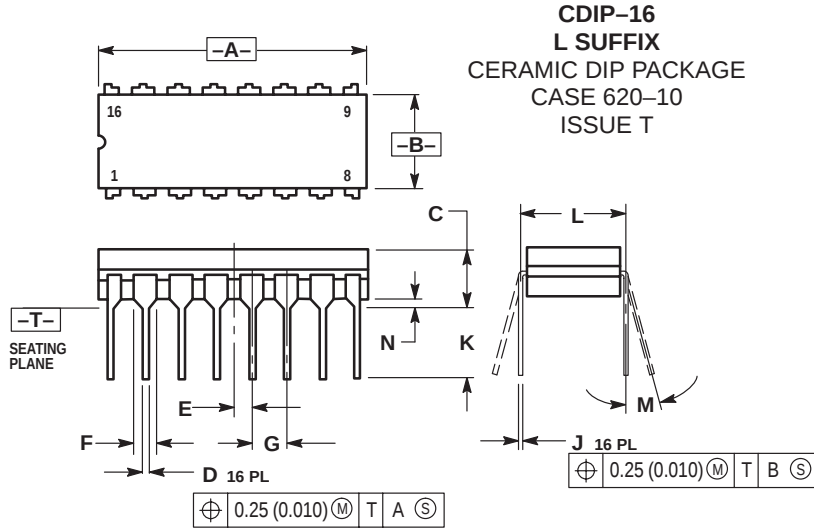
NOTES:

- DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.
- DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.
- DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.385	0.395	9.78	10.03
B	0.385	0.395	9.78	10.03
C	0.165	0.180	4.20	4.57
E	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050 BSC		1.27 BSC	
H	0.026	0.032	0.66	0.81
J	0.020	—	0.51	—
K	0.025	—	0.64	—
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
V	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Y	—	0.020	—	0.50
Z	2 °	10 °	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040	—	1.02	—

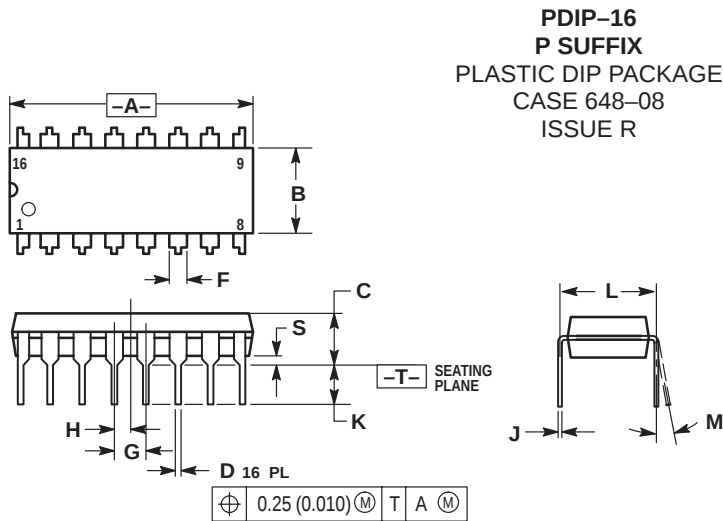
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PACKAGE DIMENSIONS



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC BODY.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.750	0.785	19.05	19.93
B	0.240	0.295	6.10	7.49
C	—	0.200	—	5.08
D	0.015	0.020	0.39	0.50
E	0.050 BSC		1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100 BSC		2.54 BSC	
H	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 5. ROUNDED CORNERS OPTIONAL.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.740	0.770	18.80	19.55
B	0.250	0.270	6.35	6.85
C	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100 BSC		2.54 BSC	
H	0.050 BSC		1.27 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10°
S	0.020	0.040	0.51	1.01

Notes

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